

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC018N04LS G	**Issued**	9. January 2019
MA#	MA004430212		
Package	PG-TDSON-8-39	**Weight***	114.08 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.071	3.57	3.57	35689	35689
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.048	0.04		424	
	non noble metal	copper	7440-50-8	48.352	42.40	42.45	423860	424411
wire	non noble metal	copper	7440-50-8	0.031	0.03	0.03	272	272
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		688	
	plastics	epoxy resin	-	6.196	5.43		54318	
	inorganic material	silicondioxide	60676-86-0	32.943	28.88	34.38	288777	343783
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13325	13325
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1389	1389
solder	non noble metal	tin	7440-31-5	0.066	0.06		576	
	noble metal	silver	7440-22-4	0.082	0.07		719	
	non noble metal	lead	7439-92-1	3.135	2.75	2.88	27484	28779
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2605	2609
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.150	0.13		1315	
	non noble metal	copper	7440-50-8	16.910	14.82	14.96	148235	149743
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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